

# Moldex3D cooperates with BoxCluster to increase 3D analysis speed

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Is it possible to run a 3D-Flow analysis on million-element mesh in 1 hour?

Yes, it is now possible.

Moldex3D, the leading CAE simulation analysis solution provider for the plastic injection molding industry, today announced its successful cooperation with **BoxCluster**, a leading system integrator for high-performance computing from Japan. Together they have launched a brand new "Moldex3D Speed+: Mini Supercomputer TurnKey Solution" that would increase the 3D analysis speed 4 to 5 times faster, in other words, a million-element mesh can be done within 1 hour.

Moldex3D provides high-performance parallel computing capabilities for plastic injection molding design and optimization to help customers troubleshooting from product design to development, optimizing mold configuration, reducing time to market, and maximizing return on investment. The "Moldex3D Speed+" combines Moldex3D's parallel computing technology with mini supercomputer to become a turnkey solution, making it a powerful tool that would significantly increase the whole analysis speed. Besides its great performance, the cost of this mini supercomputer is affordable for general publics.

**BoxCluster**, or "personal mini supercomputer," provides an 8-core (4CPU x 2Core) computing environment for engineers when the product is received, eliminating cluster setup from customer's hand. Besides higher processing speed, **BoxCluster** is also very silent (41.4db) and energy saving (630W) under full loading, which makes it an optimal object in the office space. It guarantees light weight to enhance its mobility, and easy to maintain. **BoxCluster** has been keeping the No.1 best selling deskside High Performance Computer (HPC) system in Japan.

Dr. Venny Yang, CEO of Moldex3D, stated: "Moldex3D is always developing and seeking new technologies in order to help customers perceive molding problems in advance, thus to achieve the greatest customer satisfaction. Cooperation with **BoxCluster** shows our effort to introduce the best from Japan to make the 3D simulation technology even more powerful. 'Moldex3D Speed+' is a big step forward, we feel very confident about this new solution, and we expect more people to benefit from it."

President & CEO of HPC Systems Inc, Teppei Ono, said: "Unlike others, Moldex3D's parallel computing performance on **BoxCluster** impresses us the most; with the same configuration of 4 CPU, it can speed up to 3.2~3.7 times faster, while the general other CAE systems generally speed up only 2.0~2.5 times. We are very excited to bring the most innovative computing technology to the molding industry."

## About Moldex3D

CoreTech System Co., Ltd. (Moldex3D) was founded in 1995, it has been providing the professional CAE analysis solution—"Moldex3D" series, for the plastic injection molding industry. Committing to provide the most advanced technologies and solutions for customers, Moldex3D has extended its sales and service to several locations overseas.

<http://www.moldex3d.com/jla/en/>

## About BoxCluster

BoxCluster is oversea project of the HPC Systems Inc, the leading system integrator of High Performance Computing (HPC) solutions. Since its inception in 2006, HPC Systems Inc. has quickly established itself as a technology and performance leader in Japanese small to mid-range HPC/CAE market leveraging the significant synergies between both companies' software and hardware engineering.

<http://www.boxcluster.com>